



Chuangxin Online Test Center Laboratory

Add: F/r 401Building A, Ying Da Feng industrial No,393,Jihua Rd.LongGang
Dis. Shenzhen China
Tel: 0755-83762185 Email: chenlp@iclab-cn.com



Report No:	SZ03032021007
Date:	2020/03/03
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Project Inspection Report

Company : Beijing Yuandachuangxin Technology LTD.
Address : Room506, 1+1Building, #10 Caihefang RD, Haidian DIS, Beijing
Sample Name : SN65LBC175AN
Manufacture : TI
Date Code : 19+
Sample Number : 250 PCS
Check Number : 2 PCS
Date of Received : 2021/02/25
Date of Tested : 2021/02/26 13:30 - 2021/02/26 15:40

WE HEREBY CERTIFY THAT:

The test(s) shown in the attachment were conducted according to the indicating procedures. We assume full responsibility for the accuracy and completeness of these tests and vouch for the qualifications of all personnel performing them.

Inspected by Engineer
Cherry

Reviewed by Project Manager
lucy

Note:

1. This report will be invalid if reproduced in whole or in part.
2. This report refers only to the specimen(s) submitted to test, and is invalid if used separately.
3. This report is only valid with the examination seal and signature of this institute.
4. The tested specimen(s) will only be preserved for thirty days from the date issued, if not collected by the applicant.
5. This report is only responsible for the samples tested.



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Analysis Summary

Solderability Analysis:

Solderability test was performed on 2 PCS samples marked with samples (#1-#2) using the dip and look methods. All devices failed solderability test. The dipped portion of the terminations is less than 95% covered by a continuous new solder coating.

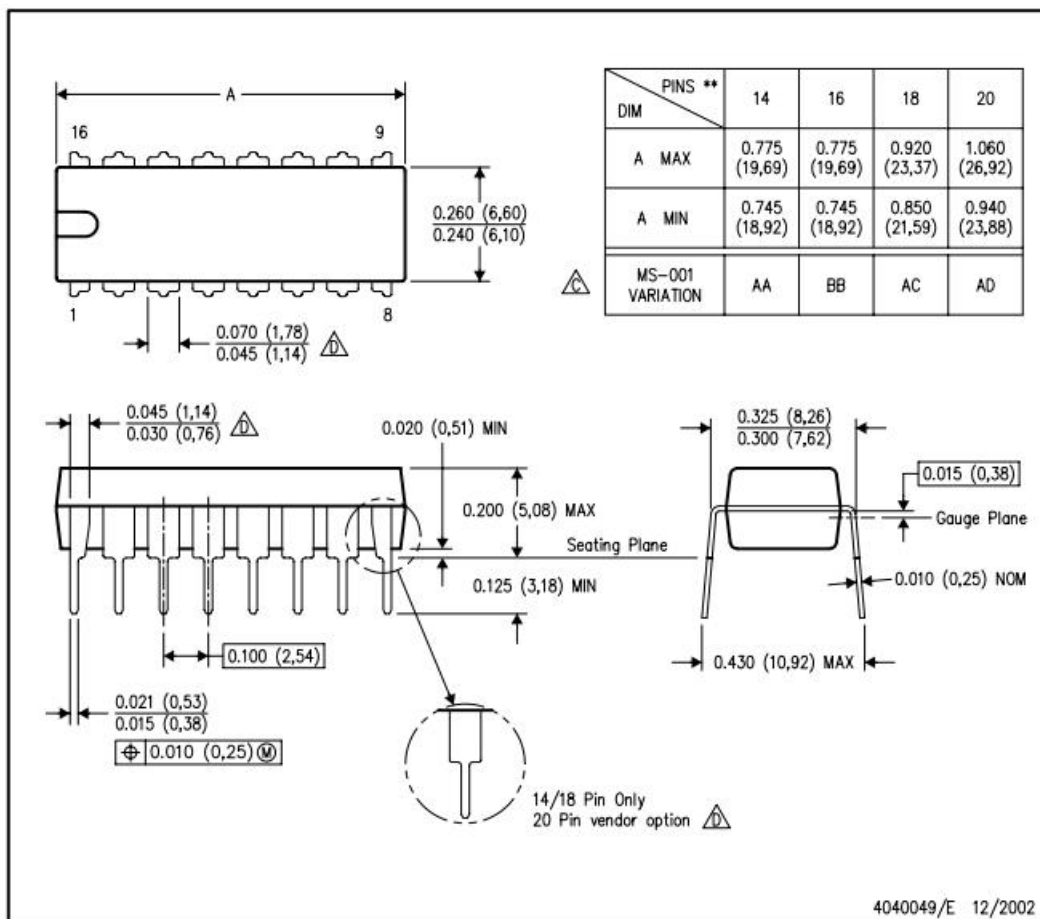


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1. Device Description:

The SN65LBC175A and SN75LBC175A are quadruple differential line receivers with 3-state outputs, designed for TIA/EIA-485 (RS-485), TIA/EIA-422 (RS-422), and ISO 8482 (Euro RS-485) applications. These devices are optimized for balanced multipoint bus communication at data rates up to and exceeding 50 million bits per second. The transmission media may be twisted-pair cables, printed-circuit board traces, or backplanes. The ultimate rate and distance of data transfer is dependent upon the attenuation characteristics of the media and the noise coupling to the environment.

2. Package dimensions:



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.



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3.Receiving Inspection:

Gross Weight:	397 g	Parts Total	250 PCS
Number Of Boxes	N/A	Intact label	Non Present
Package type	Tube	Moisture protection	Non Present
MSL	N/A	ESD protection	Acceptable

Received View-1



Received View-2



TEXAS INSTRUMENTS
 MADE IN: Mexico
 ZDC: 20:
 MSL NG/NC /NC SEAL DT
 03/24/19
 OPT:
 ITEM:
 LBL: 2A (L)T0:1585

(1P) SN65LBC175AN
 (Q) 200 (D) 1909+5
 (31T) LOT: 9058142WCI
 (4W) TKY (1T) 2050051ZDS
 (P)
 (2P) REV: A (V) 0033317
 (20L) CSD: DLN (21L) CCO: USA
 (22L) ASD: MEX (23L) ACO: MEX



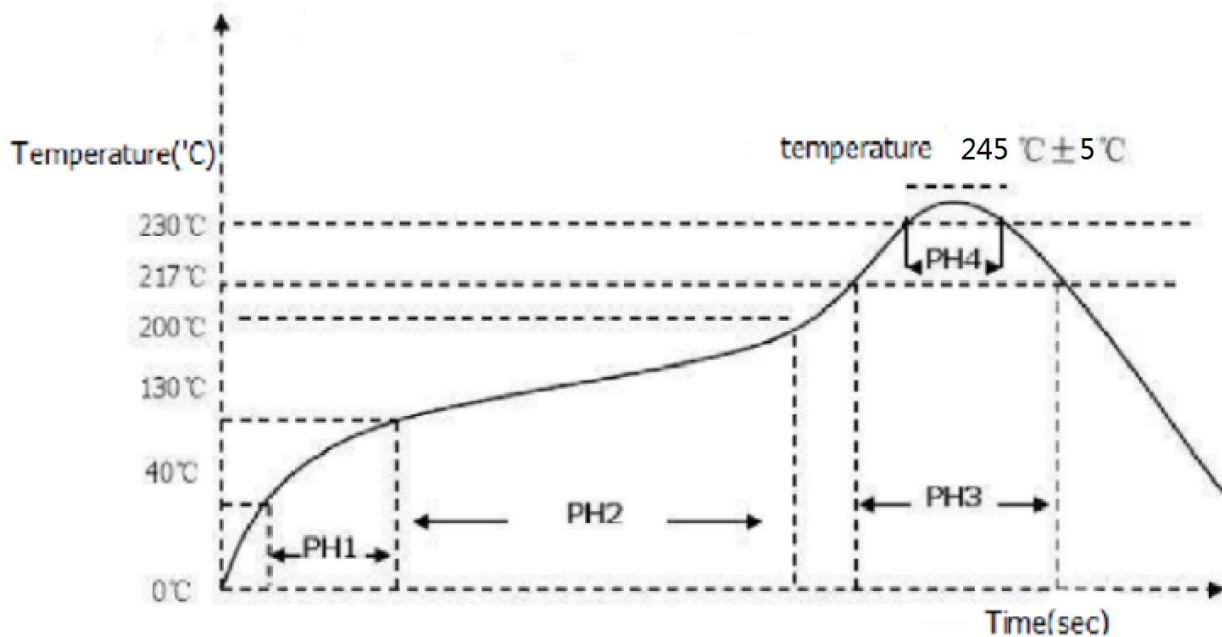
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4. Solderability Analysis:

Applicable Standard: MIL-STD-883K-2017 2003.13

Solderability test was performed on 2 PCS samples marked with samples (#1-#2) using the dip and look methods. All devices failed solderability test. The dipped portion of the terminations is less than 95% covered by a continuous new solder coating.

Testing condition:



Furnace temperature curve analysis

Room Temperature	25.4°C	Relative Humidity	45%
Immersion speed and lifting speed	0.984 in	Flux Immersion Angle	90°
Solder Pot Temperature	245°C	Solder material	Sn96.5Ag3.0Cu0.5
Solder Method	Dip and Look Test	Solder Immersion Time	5S



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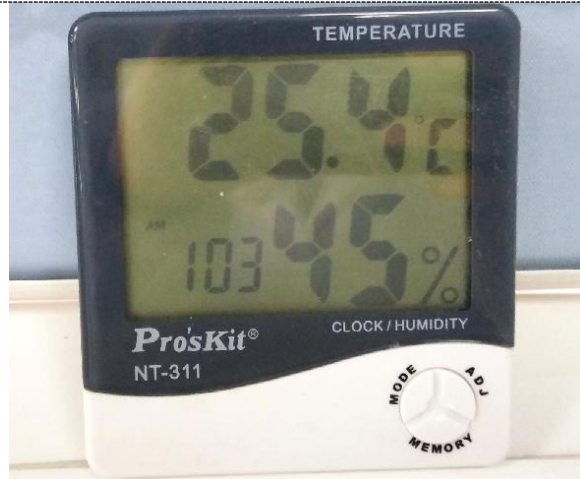
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Tin Furnace Temperature

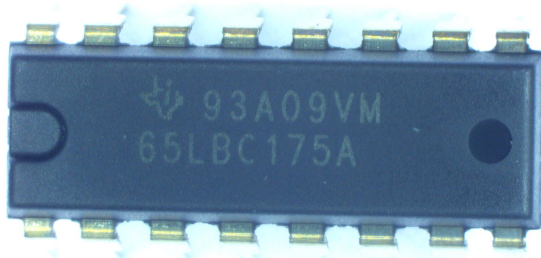


#1-Before Top View

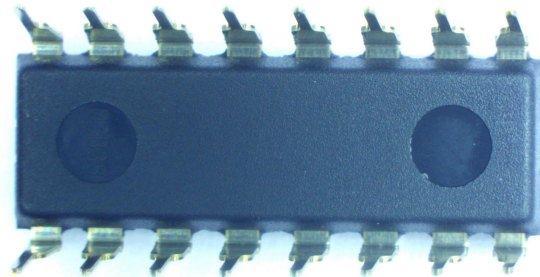
Humidity



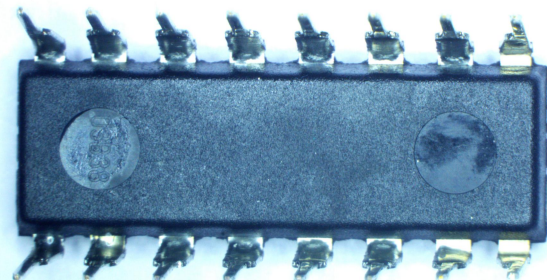
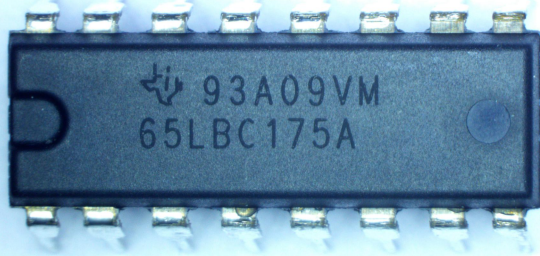
#1-Before Bottom View



#1-After Top View



#1-After Bottom View





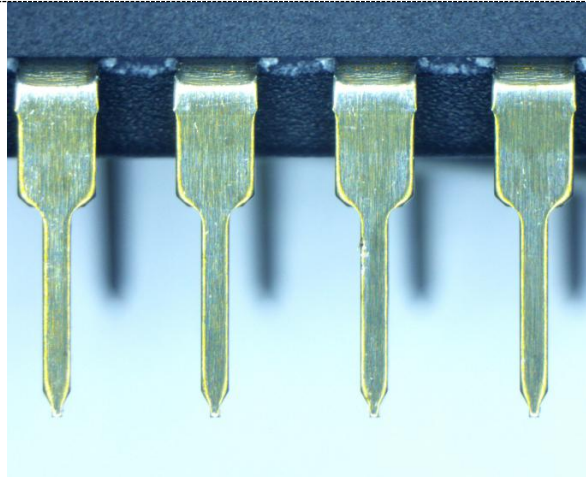
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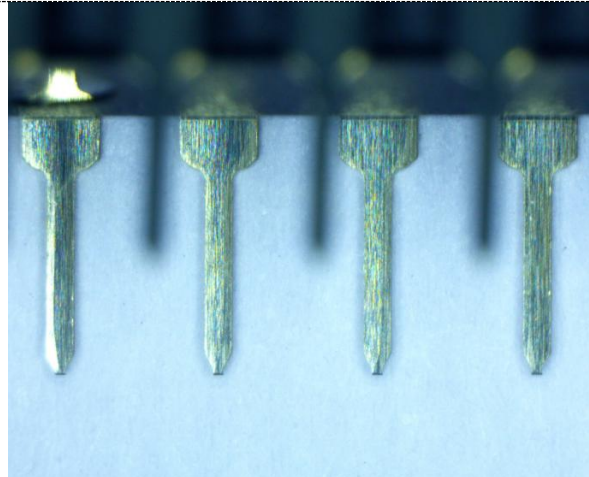


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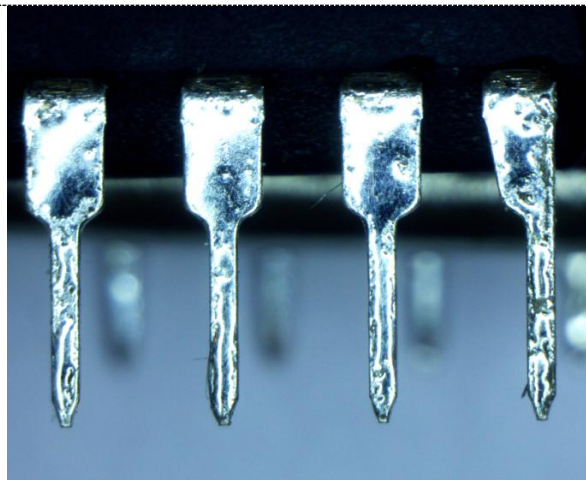
#1-Before Top Leads



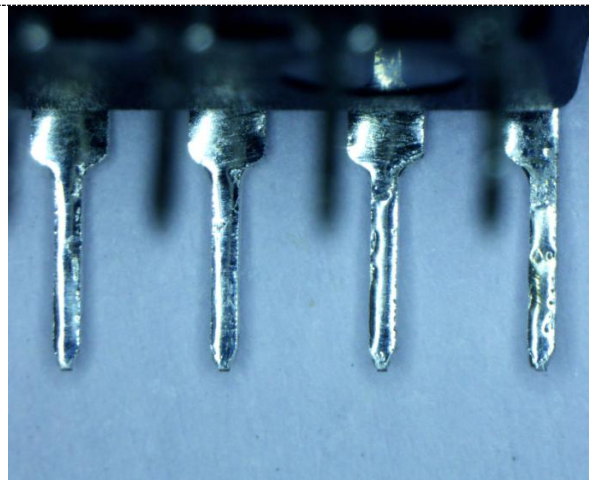
#1-Before Bottom Leads



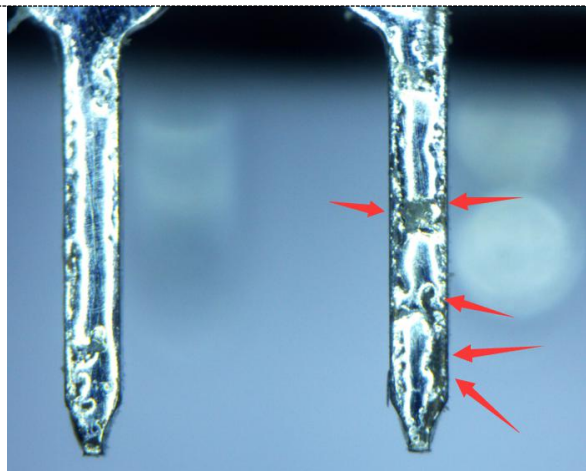
#1-After Top Leads



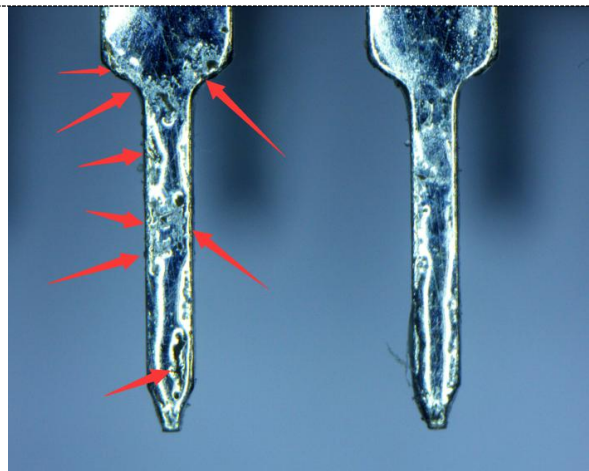
#1-After Bottom Leads



#1-Leads-1



#1-Leads-2





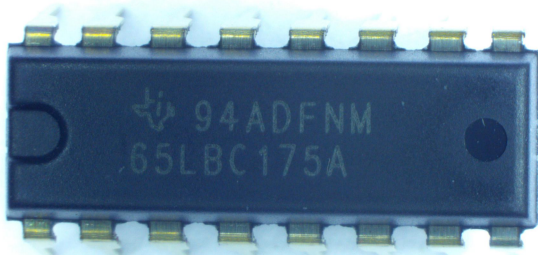
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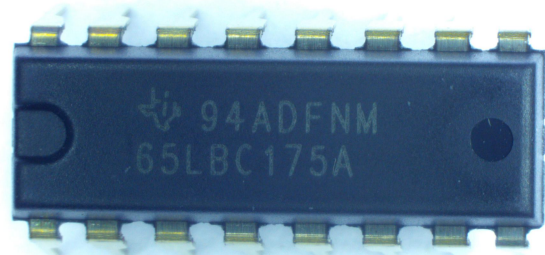


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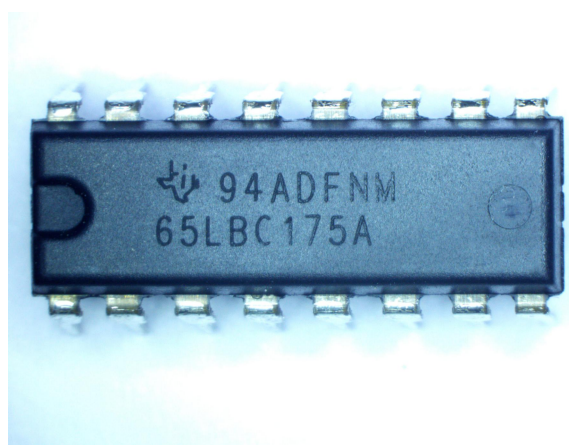
#2-Before Top View



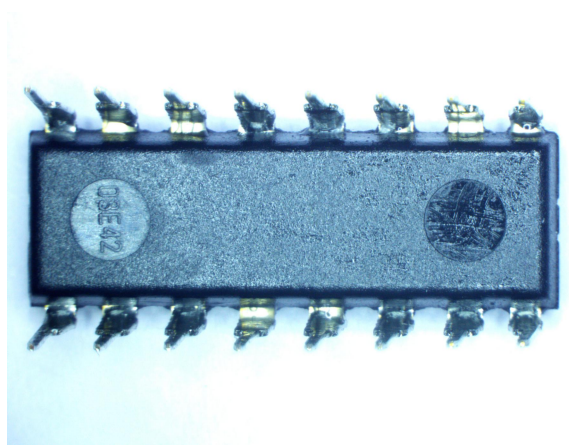
#2-Before Bottom View



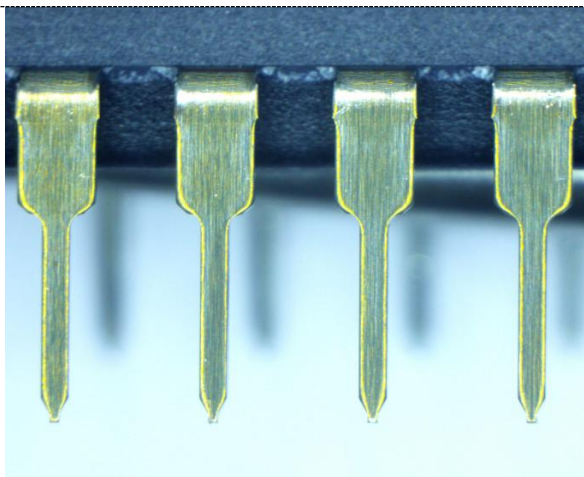
#2-After Top View



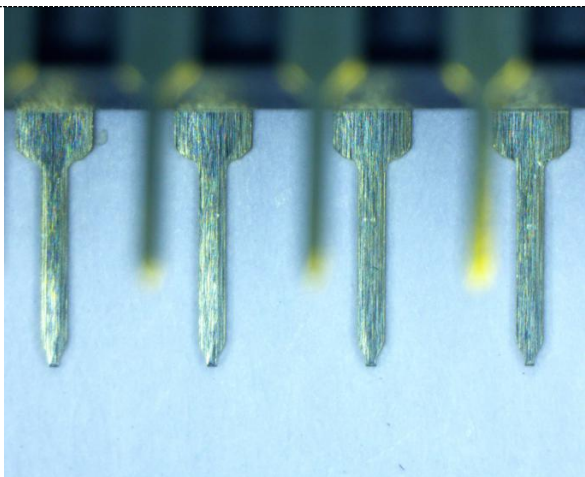
#2-After Bottom View



#2-Before Top Leads



#2-Before Bottom Leads





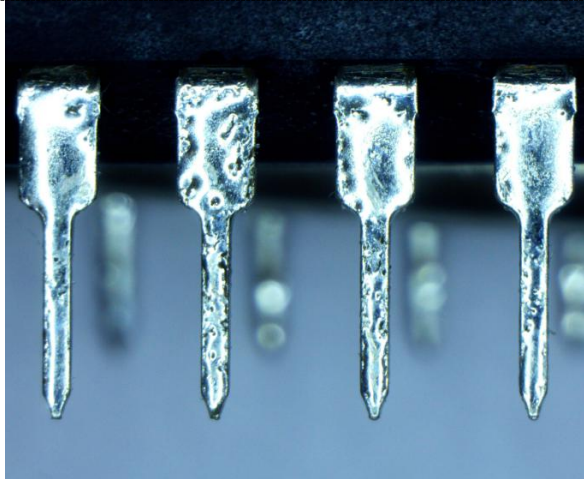
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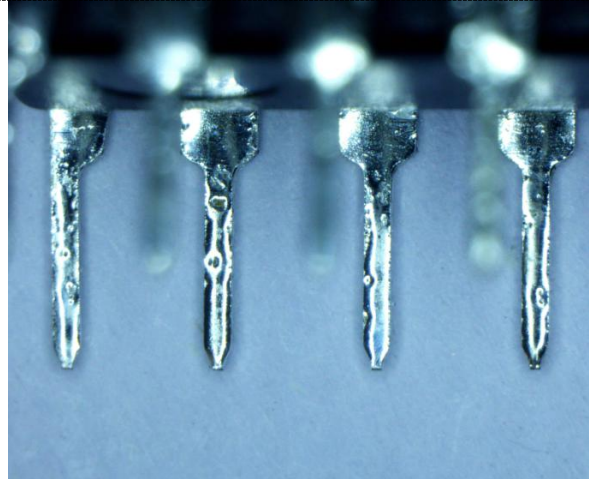


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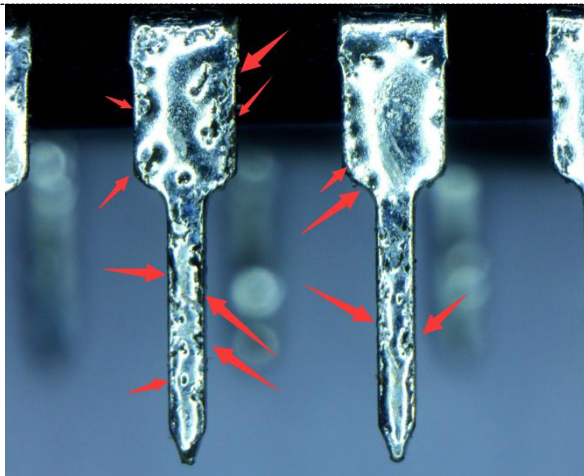
#2-After Top Leads



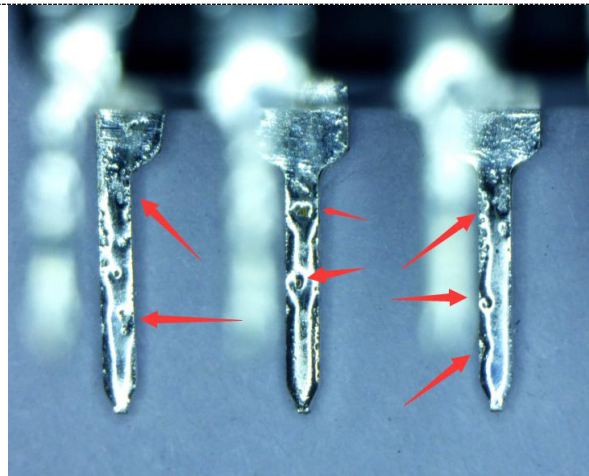
#2-After Bottom Leads



#2-Leads-1



#2-Leads-2



END



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CXO Lab WeChat official account

